



# N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)		
30	0.0046 at $V_{GS} = 10 \text{ V}$	19.8	36 nC		
	0.0054 at V <sub>GS</sub> = 4.5 V	18.2	30 110		

# **SO-8** D D D

Top View

Ordering Information: Si4362BDY-T1-E3 (Lead-(Pb)-free)

Si4362BDY-T1-GE3 (Lead-(Pb)-free and Halogen-free)

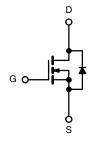
### **FEATURES**

- Halogen-free According to IEC 61249-2-21 **Available**
- TrenchFET® Power MOSFET
- Optimized for "Low Side" Synchronous **Rectifier Operation**
- 100 % R<sub>g</sub> Tested

# COMPLIANT HALOGEN **FREE**

### **APPLICATIONS**

- DC/DC Converters
- Synchronous Rectifiers



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T <sub>A</sub> = 25 °C, unless otherwise noted					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	30	V	
Gate-Source Voltage		V <sub>GS</sub>	± 12		
	T <sub>C</sub> = 25 °C		29		
Continuous Proin Current (T = 150 °C)	T <sub>C</sub> = 70 °C	I <sub>D</sub>	23		
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C		19.8 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C	]	15.8 <sup>b, c</sup>	Α	
Pulsed Drain Current		I <sub>DM</sub>	60		
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C		6		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	- I <sub>S</sub>	2.7 <sup>b, c</sup>		
	T <sub>C</sub> = 25 °C		6.6	w	
Mariana Bana Biasia Kan	T <sub>C</sub> = 70 °C	1	4.2		
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	3.0 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C	1	2 <sup>b, c</sup>		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 10 s	$R_{thJA}$	34	41	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	15	19	C/VV	

### Notes:

- a. Based on  $T_C$  = 25 °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. Maximum under Steady State conditions is 80 °C/W.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static		1001 00110110		1 - 7	1		
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V, } I_{D} = 1 \text{ mA}$	30			V	
V <sub>DS</sub> Temperature Coefficient	ΔV <sub>DS</sub> /T <sub>J</sub>			31.4		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = 250 \mu\text{A}$		- 4.9			
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	0.6		2.0	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$			1	μΑ	
	I <sub>DSS</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 19.8 A		0.0038	0.0046	Ω	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 18.2 A		0.0043	0.0054		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 19.8 A		120		S	
Dynamic <sup>b</sup>	-		I.		ı		
Input Capacitance	C <sub>iss</sub>			4800		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		500			
Reverse Transfer Capacitance	C <sub>rss</sub>			200			
Total Cata Charge	Qg	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 19.8 \text{ A}$		75	115	nC	
Total Gate Charge				36	54		
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 19.8 \text{ A}$		9			
Gate-Drain Charge	$Q_{gd}$			6.5			
Gate Resistance	$R_g$	f = 1 MHz		1.05	1.6	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			26	40		
Rise Time	t <sub>r</sub>	$V_{DD}$ = 15 V, $R_L$ = 1.5 $\Omega$		11	20	ns	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D\cong$ 10 A, $V_{GEN}$ = 4.5 V, $R_g$ = 1 $\Omega$		41	65		
Fall Time	t <sub>f</sub>			7	15		
Turn-On Delay Time	t <sub>d(on)</sub>			12	20		
Rise Time	t <sub>r</sub>	$V_{DD}$ = 15 V, $R_L$ = 1.5 $\Omega$		10	15		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		47	70		
Fall Time	t <sub>f</sub>			8	15		
<b>Drain-Source Body Diode Characteristic</b>	cs						
Continuous Source-Drain Diode Current	I <sub>S</sub>	$T_C = 25  ^{\circ}C$			6	Λ	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				60	A	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 5 A		0.7	1.1	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			35	60	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	$\frac{Q_{rr}}{t_a}$ I <sub>F</sub> = 10 A, dI/dt = 100 A/ $\mu$ s, T <sub>J</sub> = 25 °C		30	60	nC	
Reverse Recovery Fall Time	t <sub>a</sub>			18		ns	
Reverse Recovery Rise Time	t <sub>b</sub>			17			

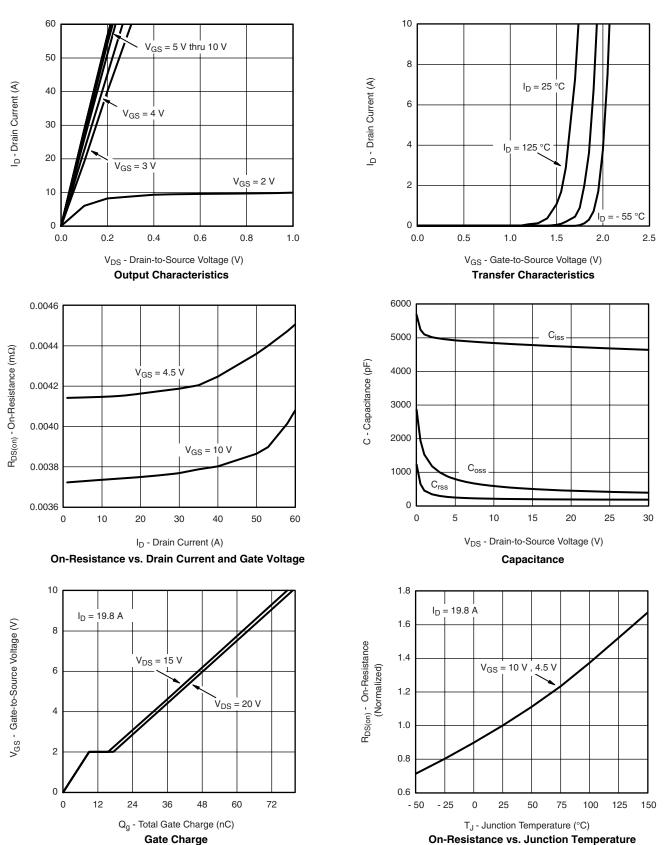
- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



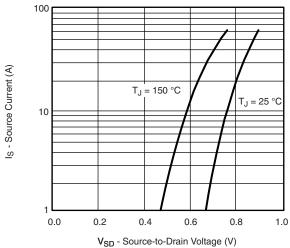


### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

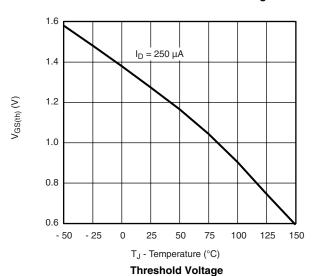


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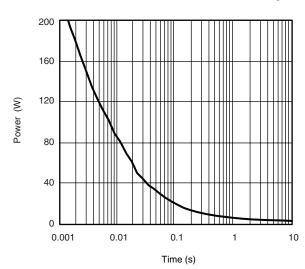


## Source-Drain Diode Forward Voltage

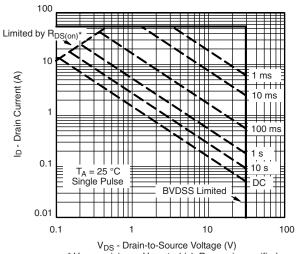


0.01  $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$  - Drain-to-Source On-Resistance  $(\Omega)$  $I_D = 19.8 A$ 0.009 0.008 0.007 T<sub>J</sub> = 125 °C 0.006 0.005 0.004  $T_J = 25$  °C 0.003 5 9

V<sub>GS</sub> - Gate-to-Source Voltage (V) On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power



\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

Safe Operating Area, Junction-to-Ambient

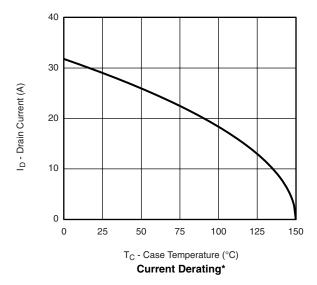


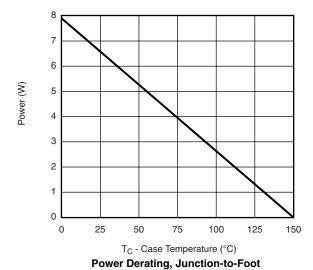




limit.

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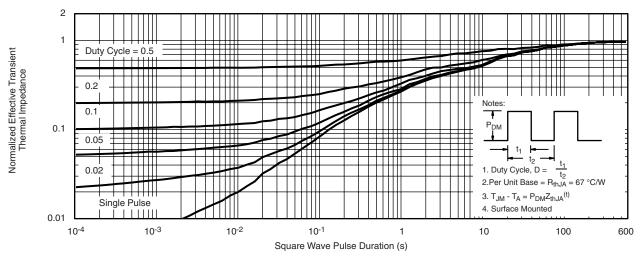
Document Number: 73539 S09-0226-Rev. B, 09-Feb-09

<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package

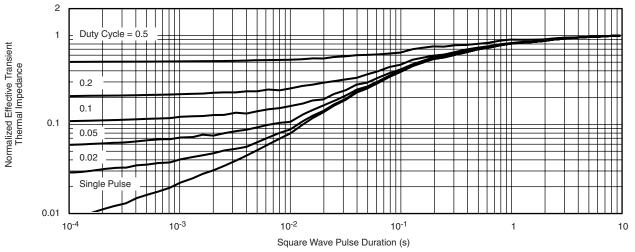
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## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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